



520.40395X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SUGIURA et al.
Serial No.: 09/930,944
Filed: August 17, 2001
For: ELECTRONIC DEVICE SEALING ELECTRONIC
ELEMENT THEREIN AND MANUFACTURING METHOD
THEREOF, AND PRINTED WIRING BOARD
Group: 2831
Examiner: H. Ngo

#10 / *[Signature]*
D. EVANS
9.12.02

SUPPLEMENTAL AMENDMENT

Assistant Commissioner
for Patents
Washington, D.C. 20231

September 6, 2002

Sir:

In supplement to the Amendment filed on September 3, 2002, please further
amend the above-identified as follows:

In the Specification:

Page 1, paragraph beginning at line 7 and continuing to page 2, has been
rewritten as indicated below:

RECEIVED
SEP - 9 2002
TECHNOLOGY CENTER 2800

The present invention relates to an electronic device, in which an electronic
element is hermetically sealed, and a method for manufacturing thereof, and further
a printed wiring board being suitable for use in such an electronic device.

B1
Conventionally, an electronic element, such as a SAW (Surface Acoustic
Wave) element, etc., is hermetically sealed within an electronic part case, for the
purpose of protecting the property or characteristics of the SAW element from being